

Appl. No. Serial No. 09/714,680
Amdt. dated September 25, 2003
Reply to Office action of June 3, 2003



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. for Reissue No. : 09/714,680
Patent No. : .6,054,198
Applicant : Bunyan *et al.*
Filed : November 16, 2002
Title : Conformal Thermal Interface
Material For Electronic Components

TC/A.U. : 1773
Examiner : D. L. Tarazano

Docket No. : 2802-257-006

Honorable Commissioner For Patents
Alexandria, VA 22313-1450

AET
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AMENDMENT UNDER 37 C.F.R. § 1.116

In response to the Office action of June 3, 2003, leave to amend the above-identified application as follows is respectfully requested:

Amendments to the Claims are reflected in the listing of the claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.

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